Material Composition Declaration

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	**Form Type *** Distribute	**Declaration Class *** Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat

Supplier Information

Company Name *	Company Unique ID	Unique ID Authority	**Response Date ***	Response Document ID	
Mindspeed Technologies, Inc			**2010-11-23**		
Contact Name *	Title - Contact	**Phone - Contact ***	**Email - Contact ***		
Cynthia Ong	Program Manager	**949-579-5515**	**cynthia.ong@mindspeed.com**		
Authorized Representative *	Title - Representative	**Phone - Representative ***	**Email - Representative** *	Supplier Comments or URL for Additional Information	
CH Choong	Senior Quality Engineer	**+6(04)-632 8036**	**ch.choong@mindspeed.com**		

	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight ***	UOM	Unit Type
	M21131G-23	M21131G-23	35HFCBGA 1156		A	ASE, Taiwan	13,756.4	mg	EACH
	Alternate Recommendation		NA		Alternate Item Comments	NA			

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
SAC	**N/A**	**5**	**245** C	**40** seconds	**3**

Comments

NA

*** Required Field**

CAS Registry Number(R) is a Registered Trademark of the American Chemical Society

Form enabled by Adobe

Save the fields in this form to a file | Export Data | Import fields from a file into this form | Import Data | Locked

RoHS Material Composition Declaration

Declaration Type * **Simplified**

RoHS Directive 2002/95/EC	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part,the terms and conditions of that agreement, including any warranty rights and or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier s liability and the Company s remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration *	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions	**Supplier Acceptance ***	**Accepted**

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version	EL-2006/690/EC

	15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature	Cynthia Ong	Digitally signed by Cynthia Ong DN: cn=Cynthia Ong Date: 2010.12.02 17:46:47 -08'00'	

*** Required Field**

Form enabled by Adobe

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

Item/SubItem Name	Homogeneous Material	Weight	Unit of Measure	Level	Substance Category	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance -	Tolerance +	PPM
M21131G-23	Die	386.83	mg	C	GROUP-C	Silicon	7440-21-3		386.83	mg			999,99
	Heatslug	9,697	mg	C	GROUP-C	Copper	7440-50-8		9,633.969	mg			993,49
				C	GROUP-C	Chrome	-		4.8485	mg			500
				B	Nickel/Nickel Compou	Nickel	7440-02-0		58.182	mg			4,229.4
	Adhesive/ TIM	180	mg	C	GROUP-C	Others	Trade Secret		18	mg			99,999
				C	GROUP-C	Alumina	01344-28-1		162	mg			899,99
	Solder ball	1,018.09	mg	C	GROUP-C	Ag	7440-22-4		30.5427	mg			30,000
				C	GROUP-C	Cu	7440-50-8		5.09045	mg			5,000
				C	GROUP-C	Sn	7440-31-5		982.4568	mg			964,99
	Substrate	2,422.1	mg	C	GROUP-C	Ag	7440-22-4		2	mg			825.72
				C	GROUP-C	CaO	1305-78-8		151	mg			62,342
				B	Antimony/Antimony C	Sb2O3	1309-64-4		22	mg			1,599.2
				C	GROUP-C	Brome compounds			72	mg			29,726
				C	GROUP-C	SiO2	7631-86-9		352	mg			145,32
				C	GROUP-C	Polyphenylene ether (PP			382	mg			157,71
				A	Lead/Lead Compound	Pb	7439-92-1		3	mg			1,238.5
				B	Bismuth/Bismuth Com	Bi	7440-69-9		5	mg			363.46
				C	GROUP-C	Sn	7440-31-5		56	mg			23,120
				C	GROUP-C	MgO	1309-48-4		38	mg			15,688
				C	GROUP-C	Epoxy resin			51	mg			21,056
				C	GROUP-C	Talc	14807-96-6		10	mg			4,128.6
				C	GROUP-C	BaSO4	7727-43-7		12	mg			4,954.3
				C	GROUP-C	Al2O3	1344-28-1		95	mg			39,222

*** Required Field**

				B	Arsenic/Arsenic Comp		As	7440-38-2		0.1	mg			7.2693
				C	GROUP-C		Cu	7440-50-8		1,171	mg			483,46
Underfill	42	mg		C	GROUP-C		Phenolic resin	9003-35-4		8.4	mg			199,99
				C	GROUP-C		Amine type accelerator	Trade Secret		2.1	mg			49,999
				C	GROUP-C		Silicon dioxide	60676-86-0		19.32	mg			459,99
				C	GROUP-C		Additives	Trade Secret		2.1	mg			49,999
				C	GROUP-C		Bisphenol F type liquid e	9003-36-5		8.4	mg			199,99
				C	GROUP-C		Bisphenol A type liquid	25068-38-6		1.26	mg			29,999
				C	GROUP-C		Carbon black	1333-86-4		0.42	mg			9,999.9
Bump	10.42	mg		C	GROUP-C		Sn	7440-31-5		6.5646	mg			629,99
				A	Lead/Lead Compound		Pb	7439-92-1		3.8554	mg			369,99